

Single-chip Type with Built-in FET Switching Regulator Series

1.0A, Step-down Switching regulators with Built-in Power MOSFET

BU90054GWZ

General Description

The BU90054GWZ are a high efficiency 6MHz synchronous step-down switching regulator with ultra low current PFM mode.

It provides up to 1.0A load current and an input voltage range from 3.0V to 5.5V, optimized for battery powered portable applications.

BU90054GWZ has a mode control pin that allows the user to select Forced PWM(Pulse Width Modulation) mode or PFM(Pulse Frequency Modulation) and PWM auto change mode utilized power save operation at light load current.

Features

- Fast transient response
- Automatic PFM/PWM operation
- Forced PWM operation
- Internal Soft Start
- Under voltage lockout
- Over current protection
- Thermal shutdown

Applications

Smart phones, Cell phones, Portable applications and Micro DC/DC modules, USB accessories

Package(s) UCSP30L1 W(Typ.) x D(Typ.) x H(Max.) 1.30mm x 0.90mm x 0.33mm

Typical Application Circuit(s)

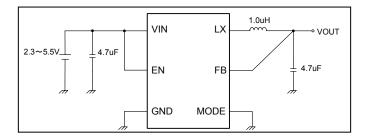


Figure 1. Typical Application Circuit(s)

Lineup

Part No.	Output	Input voltage	Switching frequency	Operati	ing mode
Tart NO.	voltage	input voltage	Switching frequency	MODE=L	MODE=H
BU90054GWZ	1.80V	2.3V to 5.5V	4.8MHz to 6.0MHz	Automatic PFM/PWM	Forced PWM

Pin Configuration(s)

(BOTTOM VIEW)

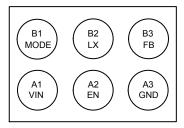


Figure 2. Pin Configuration(s)

Pin Description(s)

Pin No.	Symbol	Function
A1	VIN	Power supply input pin
A2	EN	Enable pin
A3	GND	GND pin
B1	MODE	Forced PWM mode pin
B2	LX	Inductor connection pin
B3	FB	Feedback voltage input pin

OProduct structure : Silicon monolithic integrated circuit OThis product is not designed protection against radioactive rays

Block Diagram(s)

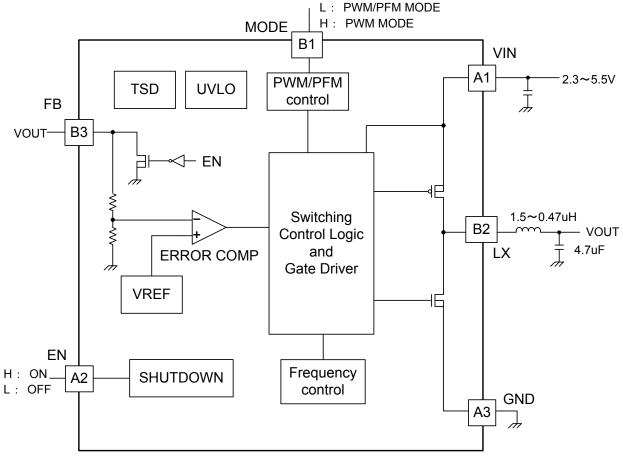


Figure 3. Block Diagram(s)

Description of Block(s)

The BU90054GWZ are a synchronous step-down DC/DC converter that achieves fast transient response from light load to heavy load by hysteretic PWM control system and current constant PFM control system.

OPWM control

BU90054GWZ operates by hysteretic PWM control. This scheme ensures fast switching, high efficiency, and fast transient response.

When the output voltage is below the VREF voltage, the error comparator output is low to high and turning on P-channel MOSFET until above the VREF voltage and minimum on time.

OPFM control

At light load the regulator and MODE=low, the regulator operates with reduced switching frequency and improves the efficiency. During PFM operation, the output voltage slightly higher than typical output voltage.

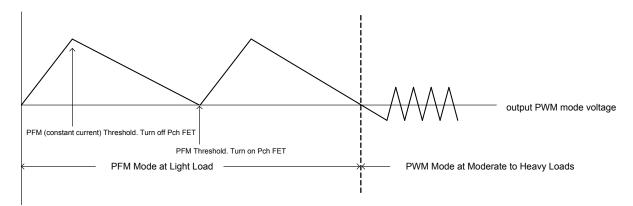


Figure 4. Operation of PFM mode and PWM mode

Description of operations

1) Shutdown

If the EN input pin set to low (<0.4V), all circuit are shut down and the regulator is standby mode. Do not leave the EN pin floating.

2) Soft start function

The regulator has a soft start circuit that reduces in-rush current at start-up. Typical start up times with a 4.7uF output capacitor is 120usec.

3) Current limit

The BU90054GWZ has a current limit circuit that protects itself and external components during overload condition.

4) UVLO

The BU90054GWZ has an Under Voltage Lock Out circuit that turn off device when VIN>2.05V(typ.)

5) FORCED PWM MODE

Setting MODE pin high (>1.4V) places the regulator in forced PWM. This control provides noise reduction and output stability. Do not leave the MODE pin floating.

6) TSD

The BU90054GWZ has a thermal shutdown feature to protect the device if the junction temperature exceeds 150°C. In thermal shutdown, the DRIVER is disabled.

This circuit is only to cut off the IC from thermal runaway, and has not been design to protect or guarantee the IC. Therefore, the user should not plan to activate this circuit with continued operation in mind.

●Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Rating	Unit
Maximum input power supply voltage	VIN	7	V
Maximum voltage at EN, FB, LX, MODE	VEN, VFB, VLX, VMODE	7	V
Power dissipation	Pd	0.39 *1	W
Operating temperature range	Topr	-40 to +85	C°
Storage temperature range	Tstg	-55 to +125	C°
Junction temperature	Tjmax	+125	C°

(*1) When mounted on the specified PCB (55mm x 63mm), Deducted by 3.9m W/c when used over Ta=25c

Recommended Operating Rating(s)

Deremeter	Symbol	Rating			11
Parameter		Min.	Тур.	Max.	Unit
Input voltage	VIN	2.3	-	5.5	V

●Electrical Characteristic(s) (unless otherwise specified VIN=3.6V, Ta=25°C)

Item		Symbol	Rating		Unit	Condition	
		Gymbol	Min.	Тур.	Max.	Onit	Condition
Switching regul	ator		. =				
Output voltage accuracy		VOUTA	1.764	1.800	1.836	v	MODE:H(PWM Operation
	j	V00///	1.764	1.800	1.854		MODE:L(PFM Operation)
		loutMAX1	-	-	1.0	A	$3.0V \leq VIN < 5.5V$
Maximum load c	urrent	loutMAX2	-	-	0.8	A	2.7V≦VIN<3.0V
		loutMAX3	-	-	0.6	A	$2.3V \leq VIN < 2.7V$
[Soft start]							
Soft start time		Tss	65	120	240	usec	
[Frequency con	trol】				1		Γ
Switching freque	ency	fosc	4.8	5.4	6.0	MHz	No load, MODE:H
[Driver]		· I			·	· · · · · · · · · · · · · · · · · · ·	
PchFET on resis	stance	RonP1	-	250	400	mOhm	VIN=5.0V
		RonP2		300	450	mOhm	VIN=3.6V
NchFET on resis	stance	RonN1	-	220	350	mOhm	VIN=5.0V
[Control]		RonN2		250	380	mOhm	VIN=3.6V
EN pin control	Operation	VENH	1.4	-	VIN	V	
voltage	Non Operation	VENL	0	-	0.4	V	
MODE pin	Operation	VMODEH	1.4	-	VIN	V	Forced PWM
control voltage	Non Operation	VMODEL	0	-	0.4	V	Automatic PFM/PWM
[UVLO]							
Protect threshold	d voltage	Uvth	1.95	2.05	2.15	V	
Hysteresis	-	Uvhy	50	100	150	mV	
[Current limit]					I		L
Current limit threshold		ILIMIT	1.5	1.7	1.9	A	PMOS current detect, Open loop
[Output discharg	ge]	L					
Output discharge resistance		DRES	55	110	220	Ohm	EN=0V
[Circuit current]							
Operating quiescent current		IINS1	-	45	65	uA	EN:H, MODE:L, VOUT=3.6V forced Not switching
Shutdown current		SHD	_	0	1	uA	EN=0V

•Electrical Characteristic curves (Reference data) Parts

L:LQM21MPN1R0NG0 (2.0mm×1.6mm×1.0mm Murata) COUT:GRM155R60J475M(1.0mm×0.5mm×0.5mm Murata)

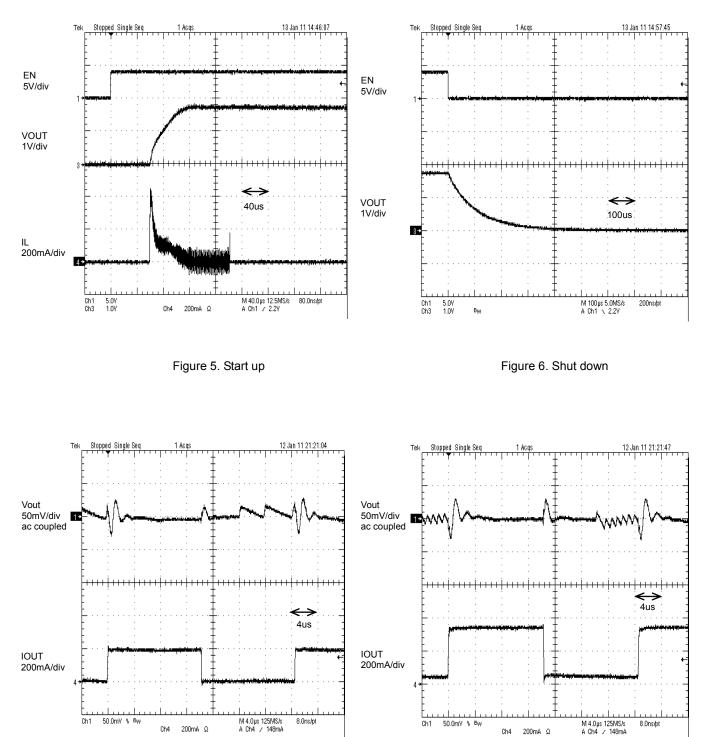


Figure 7. Load transient response 5mA to 200mA tr=tf=100ns, Mode : Low

Figure 8. Load transient response 50mA to 350mA tr=tf=100ns, Mode :Low

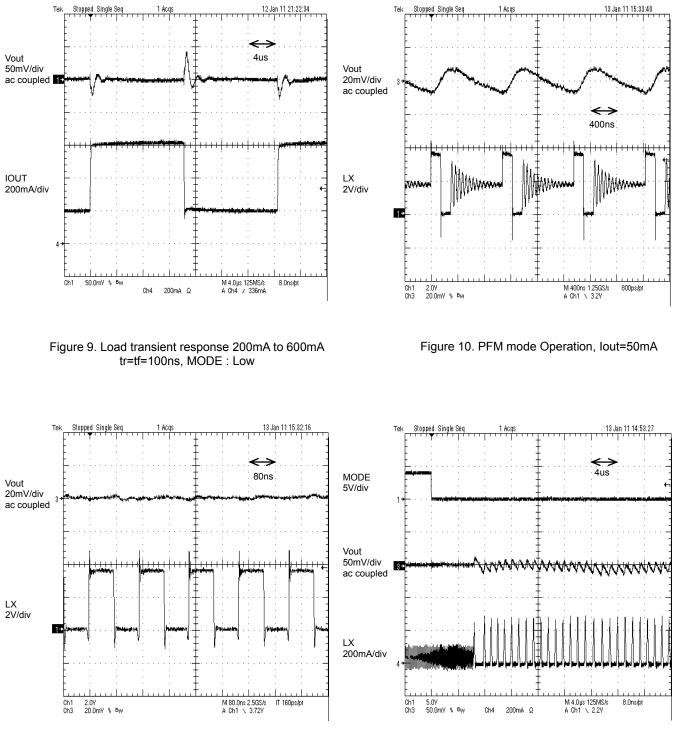
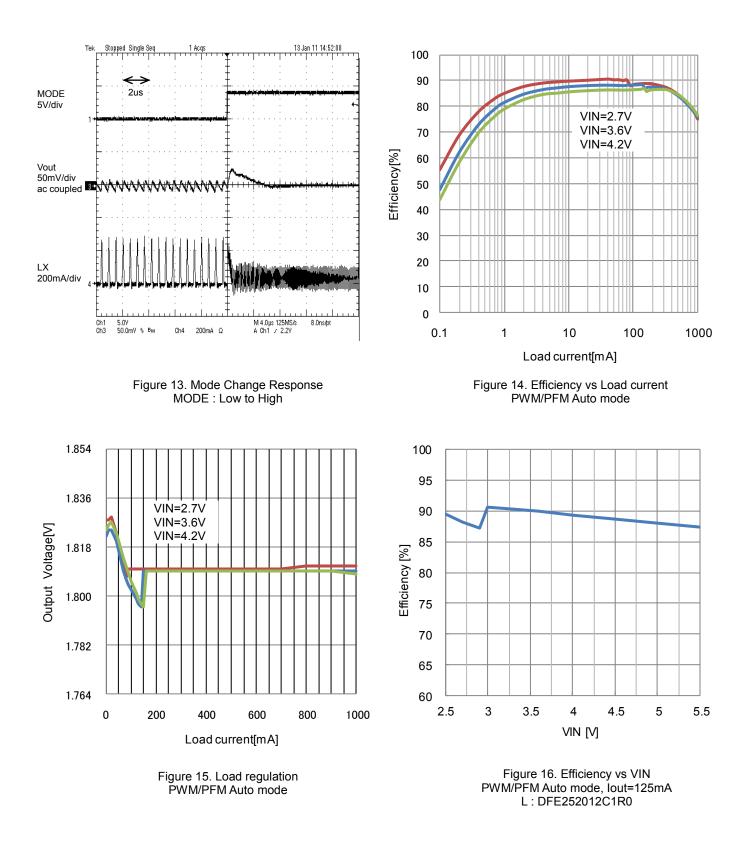
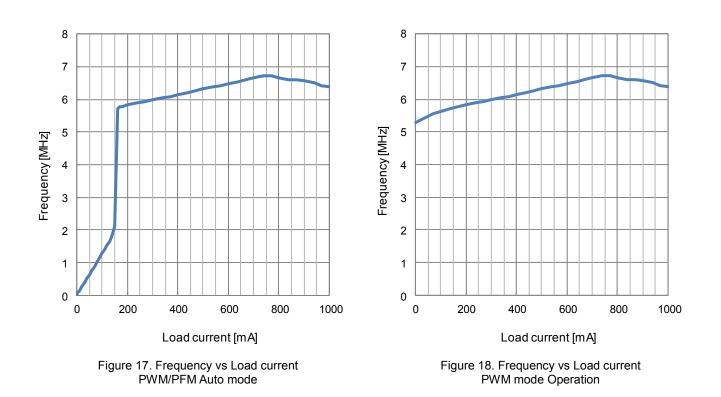


Figure 11. PWM mode Operation, lout=100mA

Figure 12. Mode Change Response MODE : High to Low





PC Board layout

The suggested PCB layout for the BU90054GWZ are shown in Figure. The following guidelines should be used to ensure a proper layout.

1) The input capacitor CIN should be connect as closely possible to VIN pin and GND pin.

2) From the output voltage to the FB pin line should be as separate as possible.

3) COUT and L should be connected as closely as possible. The connection of L to the LX pin should be as short as possible.

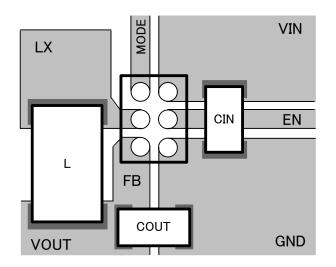


Figure 19. PCB layout

External parts selection

Inductor selection

The inductance significantly depends on output ripple current. As shown by following equation, the ripple current decreases as the inductor and/or switching frequency increase.

f: switching frequency L: inductance ΔI_L : inductor current ripple

As a minimum requirement, the DC current rating of the inductor should be equal to the maximum load current plus half of the inductor current ripple as shown by the following equation.

$$I_{LPEAK} = I_{OUTMAX} + \frac{\Box I_L}{2}$$

1) Recommended inductor selection

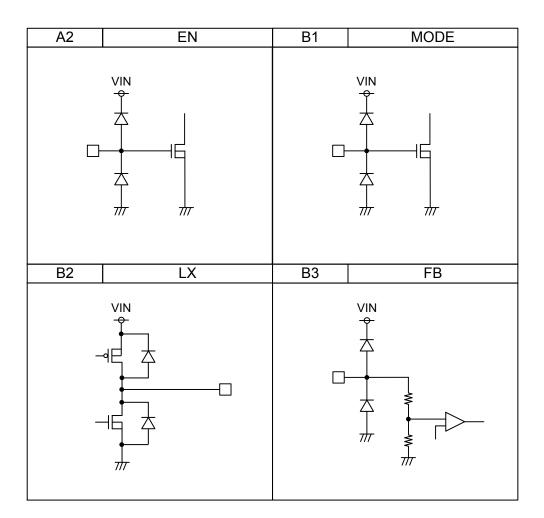
∙ lout≦1A

- LQM2MPN1R0NG0 (2.0mm × 1.6mm × 1.0mm Murata) MIPSZ2016D1R0FH (2.0mm × 1.6mm × 1.0mm FDK) DFE252012C1R0 (2.5mm × 2.0mm × 1.2mm TOKO) DFE252010C1R0 (2.5mm × 2.0mm × 1.0mm TOKO)
- lout≦0.6A

LQM21PN1R0NGC (2.0mm×1.2mm×1.0mm Murata) MIPSZ2012D1R0 (2.0mm×1.2mm×1.0mm FDK) MIPSTZ1608D1R0 (1.6mm×0.8mm×0.8mm FDK) MLP2012H1R0M (2.0mm×1.2mm×1.0mm TDK) CKP2012N1R0N (2.0mm×1.2mm×1.0mm Taiyo Yuden)

- 2) Recommended input capacitor(CIN) selection GRM155R60J225M (1.0mm × 0.5mm × 0.5mm Murata) GRM155R60J475M (1.0mm × 0.5mm × 0.5mm Murata) GRM155R60G106M (1.0mm × 0.5mm × 0.5mm Murata)
- 3) Recommended output capacitor(COUT) selection GRM155R60J475M (1.0mm × 0.5mm × 0.5mm Murata) GRM155R60G106M (1.0mm × 0.5mm × 0.5mm Murata)

●I/O equivalence circuit(s)



Caution of use

1) Absolute maximum ratings

An excess in the absolute maximum rating, such as supply voltage, temperature range of operating conditions, etc., can break down the devices, thus making impossible to identify breaking mode, such as a short circuit or an open circuit. If any over rated values will expect to exceed the absolute maximum ratings, consider adding circuit protection devices, such as fuses.

2) GND voltage

The potential of GND pin must be minimum potential in all condition. As an exception, the circuit design allows voltages

- up to -0.3 V to be applied to the IC pin.
- 3) Thermal design

Use a thermal design that allows for a sufficient margin in light of the power dissipation (Pd) in actual operating conditions.

4) Inter-pin shorts and mounting errors

Use caution when positioning the IC for mounting on printed circuit boards. The IC may be damaged if there is any connection error or if pins are shorted together.

5) Actions in strong electromagnetic field

Use caution when using the IC in the presence of a strong electromagnetic field as doing so may cause the IC to malfunction.

6) Mutual impedance

Power supply and ground wiring should reflect consideration of the need to lower mutual impedance and minimize ripple as much as possible (by making wiring as short and thick as possible or rejecting ripple by incorporating inductance and capacitance).

7) Thermal shutdown Circuit (TSD Circuit)

This model IC has a built-in TSD circuit. This circuit is only to cut off the IC from thermal runaway, and has not been design to protect or guarantee the IC. Therefore, the user should not plan to activate this circuit with continued operation in mind.

8) Regarding input pin of the IC

This monolithic IC contains P+ isolation and P substrate layers between adjacent elements in order to keep them isolated.

P-N junctions are formed at the intersection of these P layers with the N layers of other elements, creating a parasitic diode or transistor. For example, as shown in the figures below, the relation between each potential is as follows:

When GND > Pin A and GND > Pin B, the P-N junction operates as a parasitic diode.

When GND > Pin B, the P-N junction operates as a parasitic transistor.

Parasitic diodes can occur inevitable in the structure of the IC. The operation of parasitic diodes can result in mutual interference among circuits, operational faults, or physical damage. Accordingly, methods by which parasitic diodes operate, such as applying a voltage that is lower than the GND (P substrate) voltage to an input pin, should not be used.

9) Disturbance light

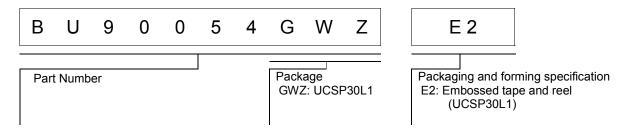
In a device where a portion of silicon is exposed to light such as in a WL-CSP, IC characteristics may be affected due to photoelectric effect. For this reason, it is recommended to come up with countermeasures that will prevent the chip from being exposed to light.

Status of this document

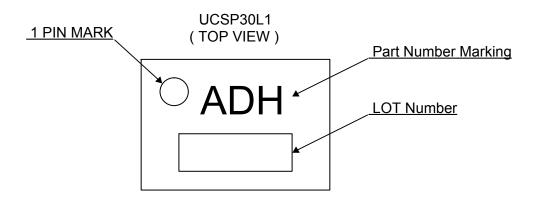
The Japanese version of this document is formal specification. A customer may use this translation version only for a reference to help reading the formal version.

If there are any differences in translation version of this document formal version takes priority

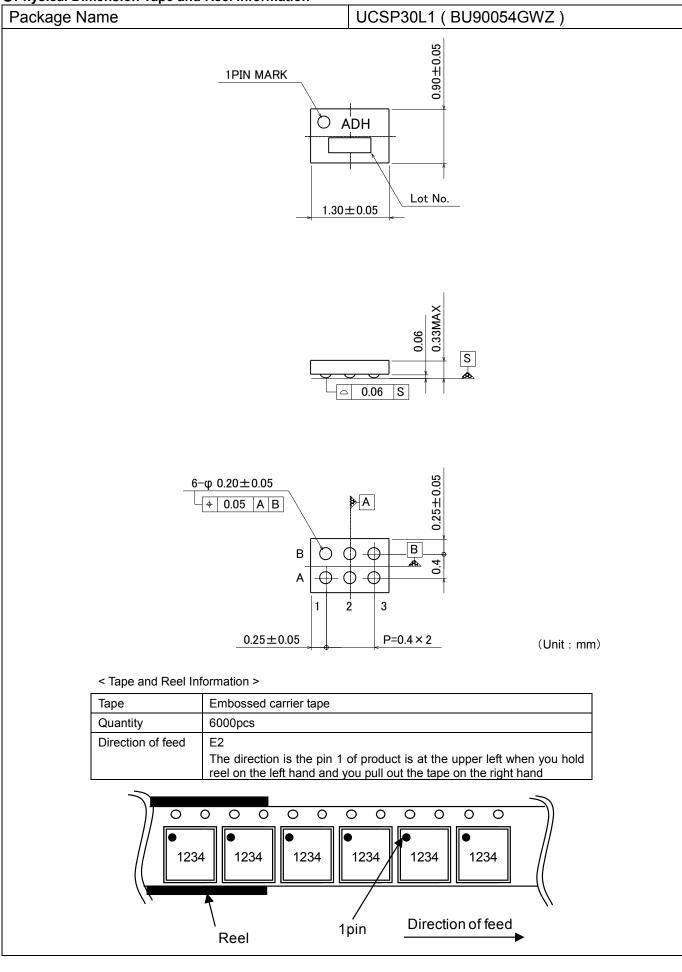
Ordering Information



Marking Diagram(s)(TOP VIEW)



Physical Dimension Tape and Reel Information



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Revision History

Date	Revision	Changes			
29.Jul.2014	001	New Release.			
8.Dec.2014	002	Page10 Recommended inductor selection DFE252010C1R0 added. Page12 Caution of use 9) Disturbance light added.			

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JAPAN	USA	EU	CHINA
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CLASSⅣ	CLASSIII	CLASSⅢ	CLASSI

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